

## Ratings Maximum operating voltage: 48 V **Connector Current Capacity** Maximum operating current: 6.5 A 10.0 **Operating Temperature Range** -25 to 85 °C, relative humidity of 85% or less 9.0 Max Current Materials (1)Insulator: PBT, black 8.0 2)Cover: PBT, black ů (3)Terminal: brass, silver plated (4)Spring plate: phosphor bronze, silver plated 7.0 Upper Temperature Limit 85 Operating Current (5) Terminal: brass, silver plated 6)Center pin: copper alloy, nickel plated Current (Amps) 6.0 **Electrical Requirements** Dielectric strength: 1 min @ 500 Vac 5.0 Insulation resistance: 100 MΩ @ 500 Vdc minimum Contact resistance: 50 mQ maximum 4.0 Mechanical Requirements (Derated) Insertion force: 0.3-1.8 kaf Operating Withdrawal force: 0.3-1.8 kgf 3.0 Area Life cycle: 5000 mating cycles while maintaining contact resistance: 100 m $\Omega$ maximum, insulation resistance: 50 M $\Omega$ 2.0 minimum, withstand voltage: 500 Vac, 1 min Terminal strength: 150 gf applied to the terminal for 15 seconds in any direction while maintaining electrical characteristics and 1.0 without damage or excessive looseness of terminals Soldering 0.0 Solderability: 75% minimum coverage when terminals dipped 2mm in 245 $\pm$ 5 °C solder bath for 3 $\pm$ 0.5 seconds 35.0 45.0 55.0 65.0 75.0 85.0 95.0 Solder bath durability: no deformation when immersed in 255 ±5 °C Ambient Temperature (°C) up to surface of the board 1.6 mm for 5 seconds or less Solder iron durability: no deformation when exposed to 350 ±10 °C Testing based on IEC 60512-5-2. Max current curve generated with isolated test article under controlled environmental conditions, for 3 ±0.5 seconds and does not take into account external factors such as housings,mating cables, or other circuitry. Operating current curve (derated by 20% of maximum values) accounts for external factors, and manufacturing variation. **Environmental Requirements** Cold test: $-25 \pm 3$ °C for 48 hours without deformation Heat test: $85 \pm 2$ °C, for 48 hours without deformation **Wave Soldering Temperature Profile** Humidity test: 40 ±2 °C, relative humidity 90-95% for 48 hours 245 °C peak (5 seconds max) without deformation Temperature (°C) Pb - Free Flow Profile Solder temperature: 245 °C 120 °C Time: 5 seconds maximum Pre-heat: 100 ~120°C 100 °C Time: 70 seconds maximum Pre-heat Measure point: surface of the solder leads 70 seconds (max) Time (S) Date: Description: Revision: Prepared: Notes: Digitally signed by AG Date: 2018.09.27 16:45:44 -07'00' TENSILITY AG А 9/20/2018 Initial release Function test: no open, no short circuit, no intermittent Verified: tel 1.541.323.3228 800 877.670.7118 JP Digitally signed by . Date: 2018.09.27 16:47:12 -07'00' fax 1.541.323.4202 web tensility.com Dimensions are in millimeters. Part number: Description: Size: Tolerances: Connector, dc jack 5.5x2.5 mm, PCB mount, 180°, 54-00149 А < 1.0: ± 0.1 mm silver plated, thru hole 1.0 to 10.0: ± 0.2 mm Scale: 5:1 OSheet 2 of 2 > 10.0: ± 0.3 mm

5

3

2